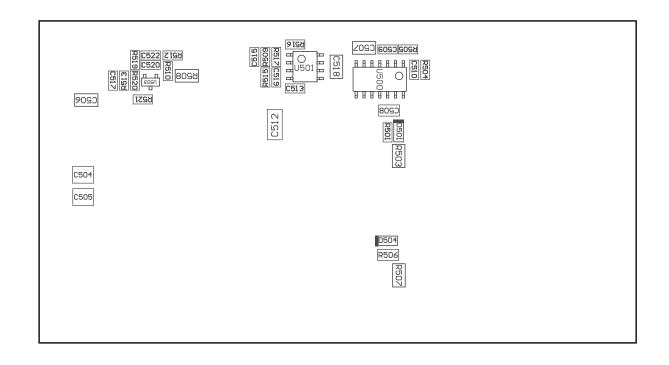


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

| PCB VIEWED FROM TOP SIDE         | BOARD #: PMP9750   | REV: B       | SVN REV: | Not In VersionControl |  |  |
|----------------------------------|--------------------|--------------|----------|-----------------------|--|--|
|                                  | TID #:             |              |          |                       |  |  |
| PLOT NAME = Top Assembly Drawing | GENERATED : 6/24/2 | 2015 8:24:36 | AM       | TEXAS INSTRUMENTS     |  |  |



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

| PCB VIEWED FROM BOTTOM SIDE         | BOARD #: PMP9750   | REV: B       | SVN REV | : Not In VersionControl |  |  |
|-------------------------------------|--------------------|--------------|---------|-------------------------|--|--|
|                                     | TID #:             |              |         |                         |  |  |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 6/24/2 | 2015 8:24:39 | AM      | TEXAS INSTRUMENTS       |  |  |

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